



## Material Content Data Sheet



Sales Product Name	SAK-XC2288H-200F100L AB			Issued		29. August 2013		
MA#	MA001035932							
Package	PG-LQFP-144-13			Weight*		1474.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	71.686	4.86	4.86	48616	48616
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.01		85	
	non noble metal	zinc	7440-66-6	0.503	0.03		341	
	non noble metal	iron	7439-89-6	10.062	0.68		6824	
	non noble metal	copper	7440-50-8	408.558	27.71	28.43	277072	284322
wire	noble metal	gold	7440-57-5	4.202	0.28	0.28	2850	2850
encapsulation	organic material	carbon black	1333-86-4	4.767	0.32		3233	
	plastics	epoxy resin	-	128.714	8.73		87290	
	inorganic material	silicondioxide	60676-86-0	819.955	55.62	64.67	556070	646593
leadfinish	non noble metal	tin	7440-31-5	9.120	0.62	0.62	6185	6185
plating	noble metal	silver	7440-22-4	2.462	0.17	0.17	1669	1669
glue	plastics	epoxy resin	-	3.600	0.24		2441	
	noble metal	silver	7440-22-4	10.800	0.73	0.97	7324	9765
*deviation	< 10%	Sum in total:				100,00		1000000

### Important Remarks:

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